

行政院國家科學委員會補助專題研究計畫成果報告

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※ 12吋矽晶圓半導體CVD製程設備及BST介 ※

※ 電薄膜成長研究(I) - 子計畫四: 利用 ※

※ CVD法成長BST薄膜與特性分析 ※

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計畫主持人：曾俊元

共同主持人：

本成果報告包括下列應繳交之附件

赴國外出差或研習心得報告一份

赴大陸地區出差或研習心得報告一份

出席國際學術會議心得報告及發表之論文各一份

國際合作研究計畫國外研究報告書一份

執行單位：國立交通大學電子工程學系

中華民國89年9月8日

12吋矽晶圓半導體 CVD 製程設備即 BST 介電薄膜成長研究 (I) -子計劃四：利用 CVD 法成長 BST 薄膜與特性分析

國科會編號：

NSC 89-2212-E009-040

主持人：曾俊元

國立交通大學電子工程系所

一．中文摘要（關鍵詞：鈦酸鋇鋇，薄膜，溶液，液相化學汽態沈積法）

流動膠體或溶液可藉液相化學汽態沈積法，旋轉法或噴霧法來製備薄膜。本研究發展了兩種溶液的製備法，並利用來在石英和氧化鋁單晶基板上製備鈦酸鋇鋇薄膜，並探討相形成的特性。另一方面並報導於氧氣和笑氣的氣氛中，濺鍍的鈦酸鋇鋇薄膜快速退火處理對其電性與介電性質之影響。

二．英文摘要（Key Words：(Ba_{1-x}Sr_x)TiO₃，thin films，solution，LSCVD）

The fluid sol or solution is ideal for preparing thin films by the processes such as liquid source chemical vapor deposition，spinning or spraying. Two methods have been used for the preparation of solution，hydroxide alkoxide precursor and acetate-alkoxide precursor. BST thin films have been deposited on quartz and sapphire substrates using these solutions. The phase formation characteristics have been investigated. In addition，we present the effect of rapid thermal annealing treatment in O₂ and N₂O ambient on the properties of rf-sputtered BST thin films.

三．結果與討論

The hydroxide-alkoxide precursors method uses the inexpensive Ba(OH)₂·8H₂O and Sr(OH)₂·8H₂O as Ba- and Sr- sources materials. The processing method is outlined in Flow Chart 1 (Fig.1). Precursor solutions were prepared using high purity Ba-，Sr- hydroxides and titanium (IV) isopropoxide (Ti(OC₃H₇)₄). For a desired composition，the required amounts of Ba-，Sr- hydroxides were separately mixed in 2-methoxy ethanol and refluxed at 120°C. Similarly，stoichiometric amount of Ti-isopropoxide was mixed 2-methoxy ethanol separately and refluxed at 120°C for 3h to form a homogeneous mixture of BST-precursor. The films were prepared by

spin coating using the solution on sapphire substrates. These films were then prebaked to evaporate the solvent at 120°C followed by baking at 400°C to pyrolyze the organics. Film of required thickness is obtained by repeating the spin coating-prebaking-baking several times before final annealing process. The phase formation characteristics are probed using X-ray diffraction. Figure 2 shows the pattern of BST (x = 0.5) deposited using this method on sapphire substrate. Interesting observation is that crystalline film is obtained at 550°C and the film shows a (101) preferred orientation up to an annealing temperature of 650°C. Film thickness of 650°C annealed

sample is 100 nm . Highly crystalline films were obtained after annealing at higher temperature without presence of a second phase .

The BST-precursor solution preparation using acetate-alkoxide precursor and film preparation procedure is outlined in Flow Chart II (Fig.3) . BST-precursor solution of required concentration (0.3-0.8M) is prepared by dissolving appropriate molar ratios of Ba- , Sr-acetate in 90°C heated glacial acetic acid followed by the addition of stoichiometric amount of Ti-isopropoxide and ethylene glycol and refluxing as outlined in flow chart . The reaction of acetic acid to ethylene glycol is critical as it determines how low the crystallization temperature of BST can be brought down . Lowest crystallization temperature is obtained for an acetic acid to ethylene glycol ratio of 3/1 . Figure 4 shows the XRD pattern of BST ($x = 0.5$) on quartz substrate . The 500 °C annealed sample is amorphous and a crystalline film is obtained at 600 °C . In order to understand the effect of post-annealing on the rf-sputtered BST thin films after deposition . The film was annealed with RTA treatment in O₂ and N₂O ambient . The annealing profile about the RTA in O₂ or N₂O treatments is shown in Fig.5 . Figures 6 and 7 show the XRD patterns of the 10% OMR BST thin films deposited on Pt bottom electrodes at 600 °C and afterward annealed for 3 min at 500 , 600 and 700 °C in O₂ and N₂O ambient . The (110) peak intensity of the BST thin films increases with increasing annealing temperature in the RTA temperature range of

500~700 °C in O₂ ambient . When BST film is annealed at 500 , 600 and 700 °C in N₂O ambient , the (110) peak intensity of the BST thin film is slightly increased with increasing temperature . It could find from Figs.6 and 7 that crystallinity of these films was improved by using RTA process . The composition of BST film deposited at 600 °C was determined from ICP-AES . The composition of BST film annealed at 500 , 600 and 700 °C in O₂ or N₂O ambient was substantially equal to the target compositions within an error of 2.2% (Ba/Sr = 0.47/0.52) . The composition of all the films obtained were consistent with cubic perovskite phase (not shown here) . Fig.8 shows the effect of RTA temperature on dielectric constant and loss tangent of the 600 °C , 10% OMR BST films deposited . The figure reveals that the dielectric constant is increased when annealing temperature is increased from 500 °C to 700 °C . According to XRD patterns in Figs.6 and 7 , the BST (110) peak is stronger for the films annealed at higher temperature . Therefore , the dielectric constant of the high temperature annealed films should be higher due to the better crystallinity . The dependence of the leakage current density measured at 100 kV/cm with a delay time of 5 sec on the RTA temperature in O₂ and N₂O ambient is shown in Figs.9 and 10 . When the RTA annealing temperature was increased to 600 °C in O₂ or N₂O ambient , both the dielectric constant and the leakage current are increased . It also shows further increase in the leakage current for the BST films annealed at 700 °C , as shown in Fig.11 .

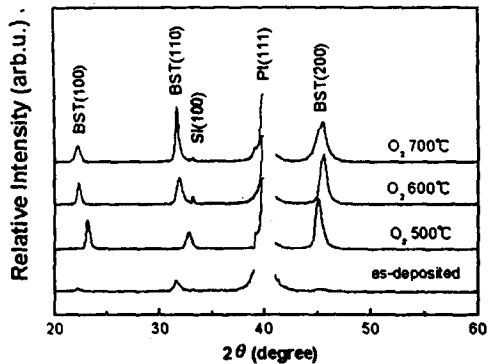


Fig. 6 XRD patterns of BST thin films deposited at 600°C with 10% OMR. The measurements were carried out at various RTA temperatures in O₂ ambient.

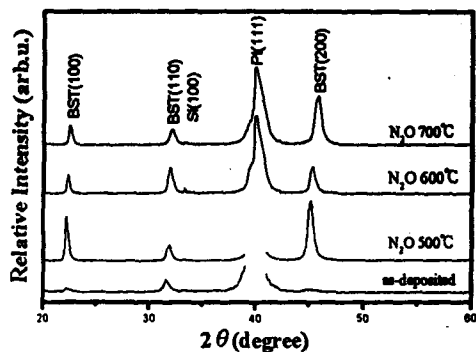


Fig. 7 XRD patterns of BST thin films deposited at 600°C with 10% OMR. The measurements were carried out at various RTA temperatures in N₂O ambient.

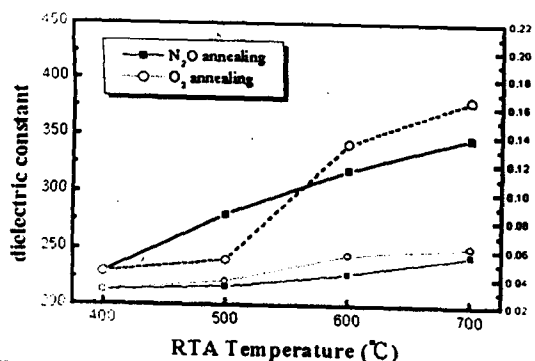


Fig. 8 Effect of RTA temperature on dielectric constant and loss tangent of the BST films deposited at 600°C with 10% OMR.

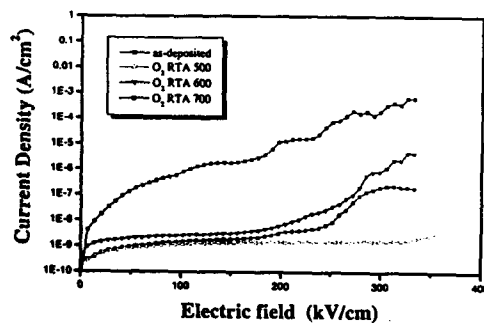


Fig. 9 Leakage current density versus applied voltage for the BST thin film deposited at 600°C with 10% OMR. The measurements were carried out at various RTA temperatures in O₂ ambient.

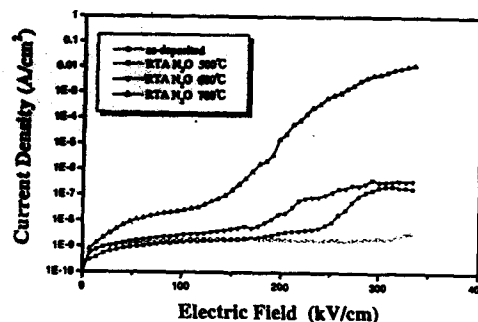


Fig. 10 Leakage current density versus applied voltage for the BST thin film deposited at 600°C with 10% OMR. The measurements were carried out at various RTA temperatures in N₂O ambient.

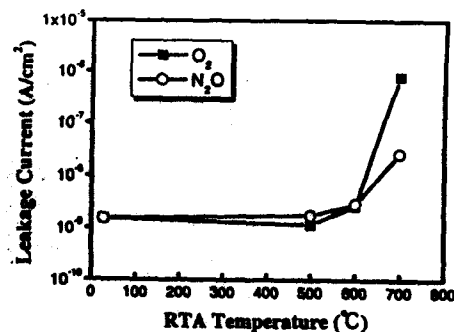


Fig. 11 Effect of RTA temperature on leakage current of 10% OMR BST films deposited at 600°C.